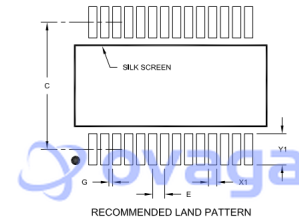


CAN Bus, Controller with Transceiver, SPI, 1, 1, 2.7 V, 5.5 V, SSOP

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

Manufacturers	Microchip Technology, Inc
Package/Case	SSOP-28
Product Type	Interface ICs
RoHS	
Lifecycle	



Dimension	UNITS		MILLIMETERS	
	MIN	NCM	MIN	MAX
Contact Pitch	E		0.69 BSC	
Contact Pad Spacing	C		2.20	
Contact Pad Width (X1)	X1			0.45
Contact Pad Length (Y1)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:
 1. Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension, Theoretically exact value shown without tolerances.
 Microchip Technology Drawing No. 004-2073A

Images are for reference only

Please submit RFQ for MCP25625-E/SS or [Email to us: sales@ovaga.com](mailto:sales@ovaga.com) We will contact you in 12 hours.

[RFQ](#)

General Description

The MCP25625 is a complete, cost-effective and small-footprint CAN solution that can be easily added to a microcontroller with an available SPI interface. The MCP25625 interfaces directly with microcontrollers operating at 2.7V to 5.5V, there are no external level shifters required. In addition, the MCP25625 connects directly to the physical CAN bus, supporting all requirements for CAN high-speed transceivers. The MCP25625 meets the automotive requirements for high-speed (up to 1 Mb/s), low quiescent current, electromagnetic compatibility (EMC) and electrostatic discharge (ESD)

Please see our MikroElektronika click Board! <http://www.mikroe.com/click/mcp25625>

Features

Stand-Alone CAN2.0B Controller with Integrated CAN Transceiver and Serial Peripheral Interface (SPI)

Up to 1 Mb/s Operation

Very Low Standby Current (10 μ A, typical).

Up to 10 MHz SPI Clock Speed

Interfaces Directly with Microcontrollers with 2.7V to 5.5V I/O

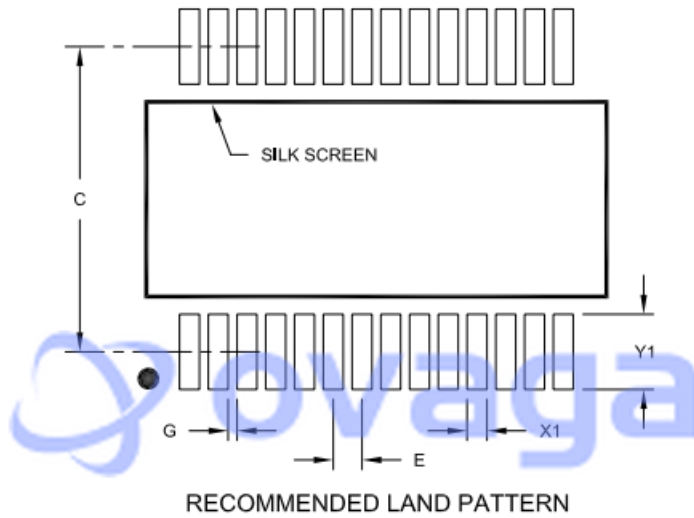
Available in SSOP-28L and 6x6 QFN-28L

Temperature Ranges:

Extended (E): -40°C to +125°C

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

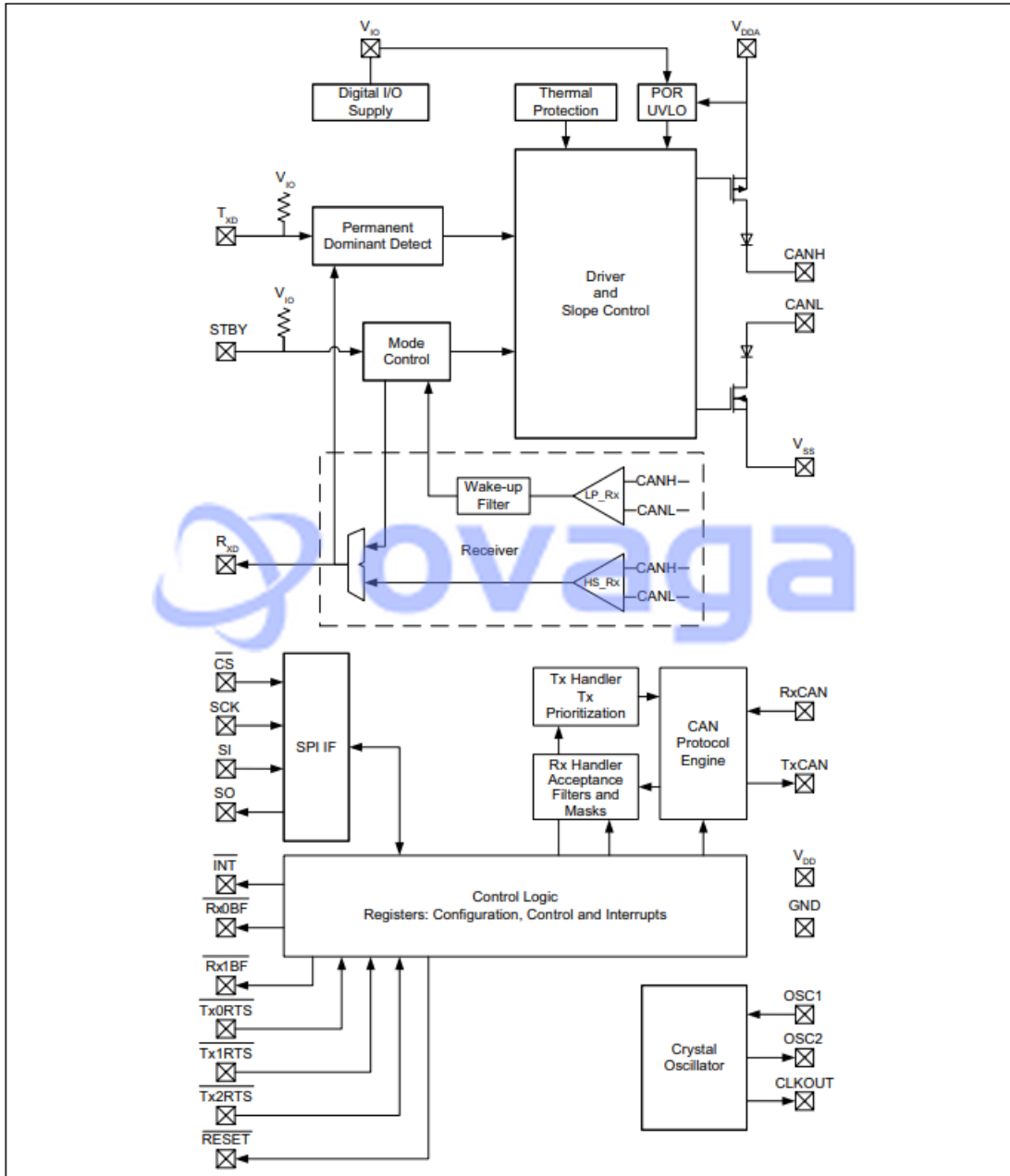
Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension, Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

FIGURE 1-1: MCP25625 BLOCK DIAGRAM



Related Products



[MCP23008T-E/SO](#)

Microchip Technology, Inc
SOIC-18



[MCP2551-I/P](#)

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[MCP2210-I/SO](#)

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[MCP23008T-E/ML](#)

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[MCP2515T-I/SO](#)

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SOIC-8